

### Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Peak Blocking Voltage	600	V <sub>P</sub>
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	A
Input Power Dissipation <sup>1</sup>	100	mW
Total Package Dissipation <sup>2</sup>	550	mW
Isolation Voltage, Input to Output	5000	V <sub>rms</sub>
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	٥C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

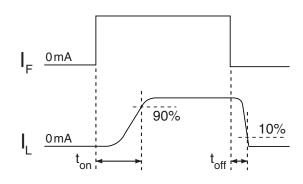
<sup>1</sup> Derate linearly 1.33mW / °C <sup>2</sup> Derate linearly 3mW / °C

Electrical Characteristics @ 25°C

Parameters	Conditions	Symbol	Min	Тур	Max	Units	
Output Characteristics		· · · · ·				1	
Load Current							
Continuous	-	IL I	-	-	90	mA <sub>rms</sub> / mA <sub>DC</sub>	
Peak	t=10ms	I <sub>LPK</sub>	-	-	±350	mA <sub>P</sub>	
On-Resistance 1	I <sub>L</sub> =90mA	R <sub>ON</sub>	-	35	50	Ω	
Off-State Leakage Current	V <sub>L</sub> =600V <sub>P</sub>	I <sub>LEAK</sub>	-	-	1	μΑ	
Switching Speeds							
Turn-On	I <sub>F</sub> =5mA, V <sub>L</sub> =10V	t <sub>on</sub>	-	-	5		
Turn-Off	(See Timing Diagram)	t <sub>off</sub>	-	-	5	ms	
Output Capacitance	I <sub>F</sub> =0mA, V <sub>L</sub> =50V, f=1MHz	C <sub>OUT</sub>	-	50	-	pF	
Input Characteristics		•					
Input Control Current to Activate	I <sub>L</sub> =90mA	I <sub>F</sub>	-	0.55	2	0	
Input Control Current to Deactivate	-	I <sub>F</sub>	0.2	-	-	- mA	
Input Voltage Drop	I <sub>F</sub> =5mA	V <sub>F</sub>	0.9	1.2	1.4	V	
Reverse Input Current	V <sub>R</sub> =5V	I <sub>R</sub>	-	-	10	μΑ	
Common Characteristics		· · ·					
Input to Output Capacitance	V <sub>IO</sub> =0V, f=1MHz	C <sub>IO</sub>	-	3	-	pF	

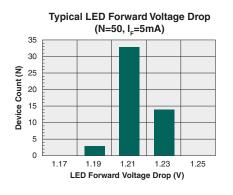
<sup>1</sup> Measurement taken within 1 second of on-time.

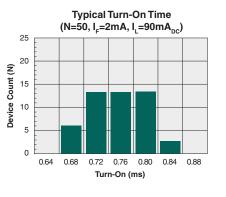
# **Timing Diagram**

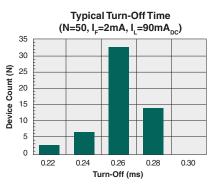




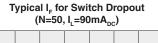
# PERFORMANCE DATA @25°C (Unless Otherwise Noted)\*

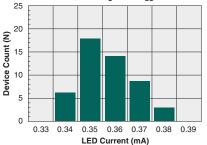


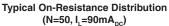


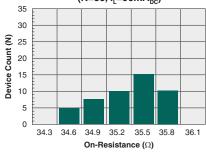


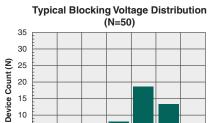
Typical I<sub>c</sub> for Switch Operation (N=50, I\_=90mA<sub>DC</sub>) 25 20 Device Count (N) 15 10 5 0 0.53 0.54 0.55 0.56 0.57 0.58 0.59 LED Current (mA)





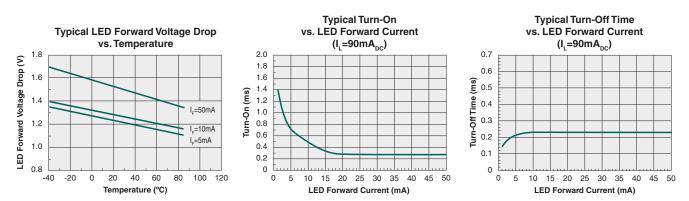






5 0 777

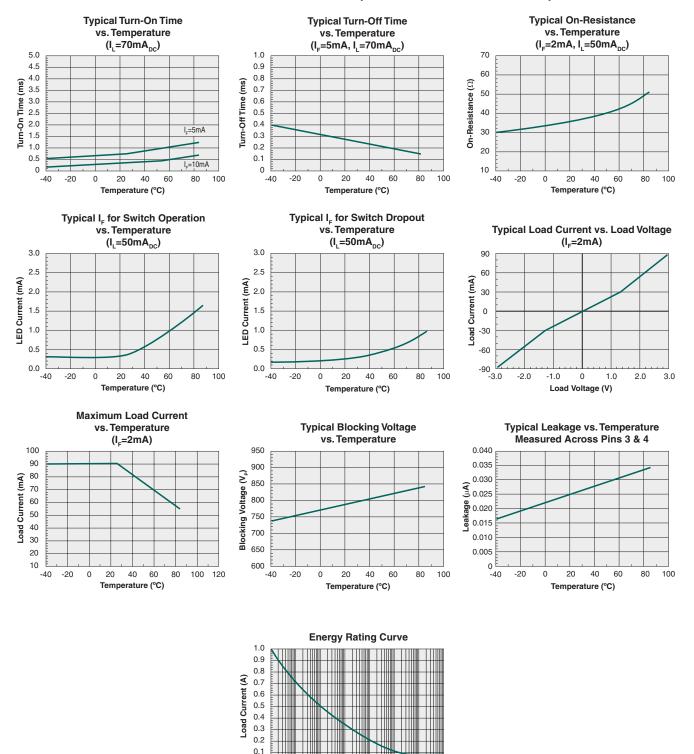
782 787 792 797 802 807 Blocking Voltage (V<sub>p</sub>)



\*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.



## PERFORMANCE DATA @25°C (Unless Otherwise Noted)\*



\*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

 $100 \mu s$  1ms 10ms 100ms

Time

1s

10s 100s

0 E⊥ 10µs



## **Manufacturing Information**

#### **Moisture Sensitivity**

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating	
CPC1393G / CPC1393GV	MSL 1	
CPC1393GR	MSL 3	

#### **ESD Sensitivity**



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

#### **Soldering Profile**

Provided in the table below is the Classification Temperature ( $T_c$ ) of this product and the maximum dwell time the body temperature of this device may be above ( $T_c$  - 5)°C. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. Additionally, for the CPC1393GR, the solder reflow profile given in Technical Brief TB-200 "**Pb-Free Solder Reflow Profile for Select Devices**" must be followed. For the through-hole devices, CPC1393G and CPC1393GV, and any other processes, the guidelines of **J-STD-020** must be observed.

Device	Maximum Body Temperature ( ${\sf T}_{\sf c}$ )	Time
CPC1393GR	250°C	15 seconds

#### **Board Wash**

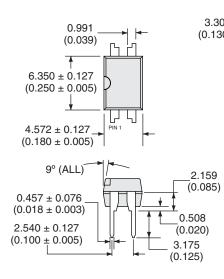
IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow-up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device, and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.

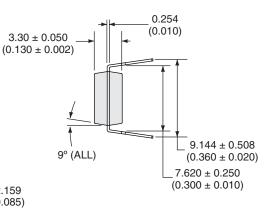




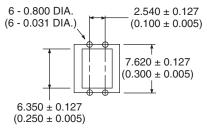
# **MECHANICAL DIMENSIONS**

### CPC1393G





#### PC Board Pattern (Top View)



Dimensions mm (inches)

### **CPC1393GV**

0.991

(0.039)

6.350 ± 0.050 (0.250 ± 0.002)

<u></u>4.572 ± 0.050

 $(0.180 \pm 0.002)$ 

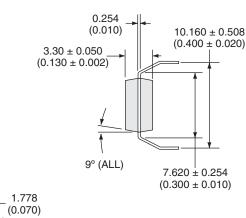
 $0.457 \pm 0.076$ (0.018 ± 0.003)

 $2.540 \pm 0.050$ 

 $(0.100 \pm 0.002)$ 

9° (ALL)

Pin 1



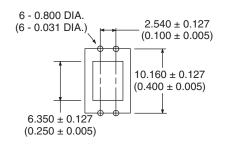
0.127

(0.005)

2.92

(0.115)

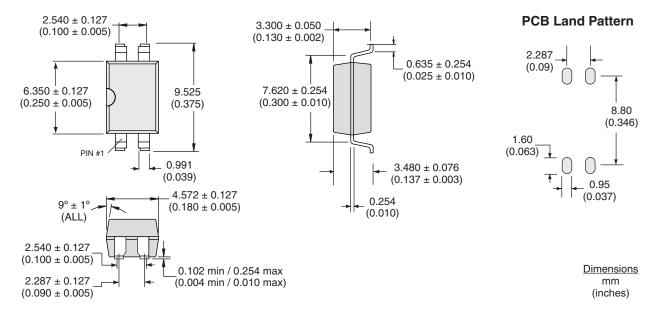
### PC Board Pattern (Top View)



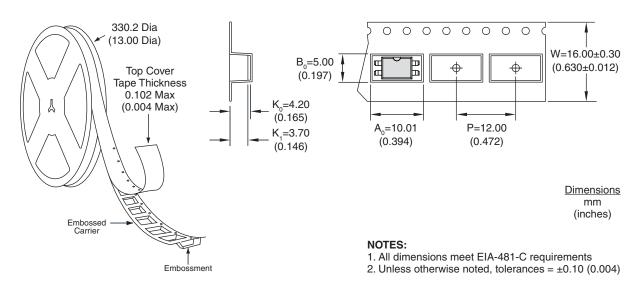
Dimensions mm (inches)



### **CPC1393GR**



## CPC1393GRTR Tape & Reel



#### For additional information please visit our website at: www.ixysic.com

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